



#10/B
2-12-03
Mullish

Docket No.: M4065.0082/P082-A

RECEIVED
FEB 10 2003
TECHNOLOGY CENTER 2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Paul A. Farrar

Application No.: 09/638,026

Group Art Unit: 2811

Filed: August 14, 2000

Examiner: N. Parekh

For: METHOD OF FORMING A MICRO
SOLDER BALL FOR USE IN C4
BONDING PROCESS

AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated November 5, 2002 (Paper No. 9),
rejecting claims 40, 43-51, and 68-72, please amend the above-identified patent application
as follows:

In the Claims

Please amend the following claims as indicated.

40. (Twice amended) A semiconductor device comprising:

B'
a semiconductor structure having at least one metal contact formed on a
surface thereof;

a first insulator layer overlying said at least one metal contact;

at least one metal pad overlying said first insulator layer and in contact with